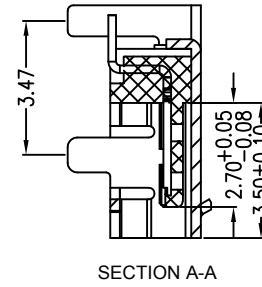
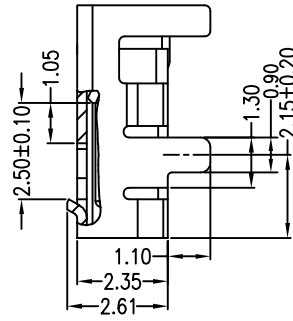
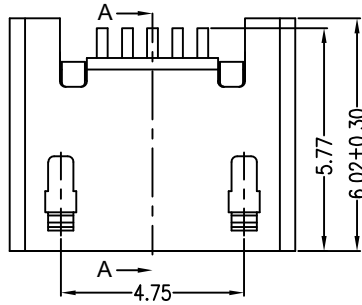


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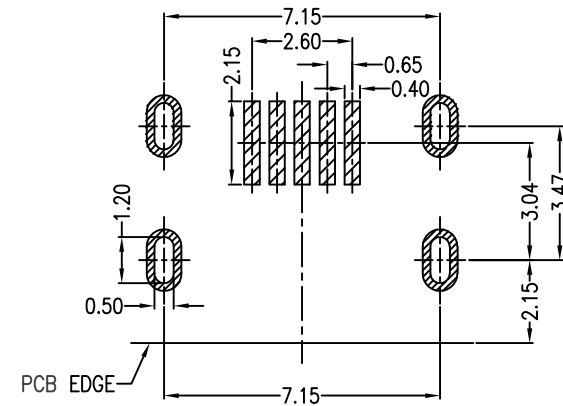
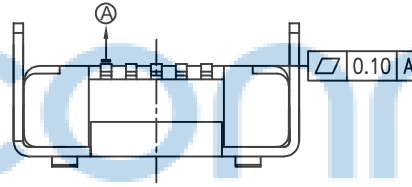
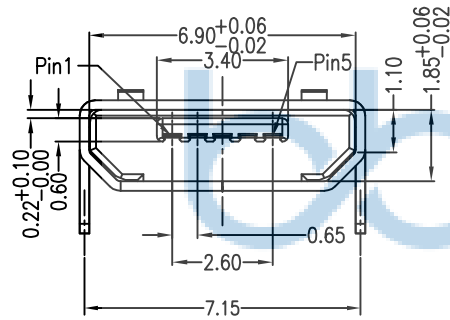
Note:

1. Material:

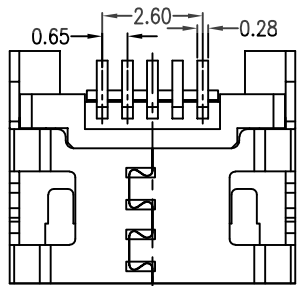
- 1.1 Housing: High temperature thermoplastic with g. f, UL94v-0
- 1.2 Contact: copper alloy, t=0.20mm
- 1.3 Shell: copper alloy, t=0.25mm

2. Specification:

- 2.1 Current rating: 1, 5PIN 1.8A Max/2, 3, 4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temperature range: -30° C~80° C



RECOMMENDED PCB LAYOUT
PCB图仅供参考



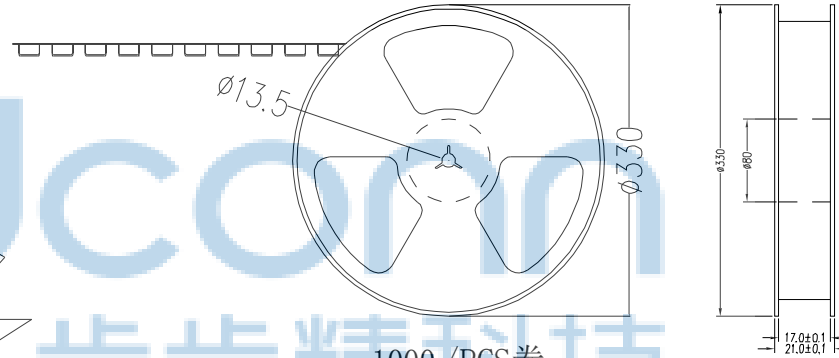
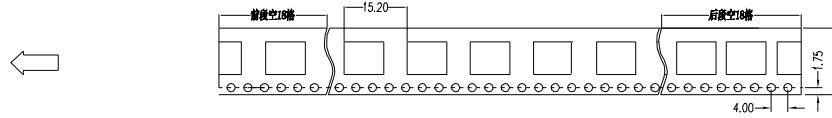
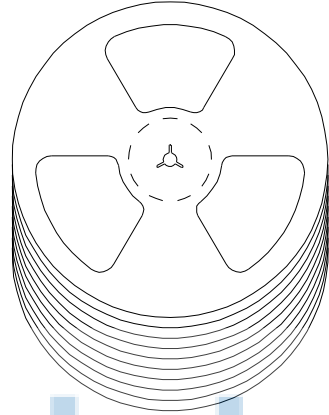
Since 1987

步步精科技



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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X': ±3" .X': ±2" .XX': ±1"	
PJ. NO.: MC. 01. 22-21-1001 SIZE: A4 FINISH: SEE NOTES SCALE: N/A		MAT'L.: SEE NOTES REV.: A3 UNIT: mm PAGE: 1/1	

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0			2023 20/04	



备注: 1000 /PCS 卷

1. 包装数量: 1000 /PCS/卷, 10卷/箱或15卷/箱。
2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
3. 材质:
载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$
上带: 聚乙烯 (PET), 阻抗 $10^{6-11} \Omega$
卷盘: 聚苯乙烯。

纸箱规格: 345*345*23MM
纸箱规格: 345*345*35MM



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APPD.	JM_Zheng	23/05'02	NAME: Micro-5P 母座 90度 L=6.0 四脚插 无柱 亮锡 平口 铜壳
CHKD.	LYX	23/05'02	PJ. NO.: MC. 01. 22-21-1001
DR.	SGF	23/05'02	SIZE: A4 DRW NO.:
PDWG.NO: 0113-1		FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1	